

Special Issue

Sensing and Processing for 3D Computer Vision: 3rd Edition

Message from the Guest Editor

This Special Issue welcomes the submission of research articles that address 3D sensing technology in addition to the use of advanced 3D sensors in computer vision. Original contributions on novel active 3D sensors, stereo reconstruction approaches and sensor calibration techniques are solicited. Articles on 3D point cloud/mesh processing, geometric modeling, shape representation and recognition are also of interest in this Special Issue. Articles on the application of 3D sensing and modeling to metrology, industrial inspection and quality control, augmented/virtual reality, heritage preservation, arts and other fields are also welcome.

Guest Editor

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Deadline for manuscript submissions

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Message from the Editor-in-Chief

Sensors is a leading journal devoted to fast publication of the latest achievements of technological developments and scientific research in the huge area of physical, chemical and biochemical sensors, including remote sensing and sensor networks. Both experimental and theoretical papers are published, including all aspects of sensor design, technology, proof of concept and application. Sensors organizes Special Issues devoted to specific sensing areas and applications each year.

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